

BULD1101E

High voltage fast-switching NPN Power Transistor

General features

- High voltage capability
- Low spread of dynamic parameters
- Minimum lot-to-lot spread for reliable operation
- Very high switching speed
- In compliance with the 2002/93/EC European Directive

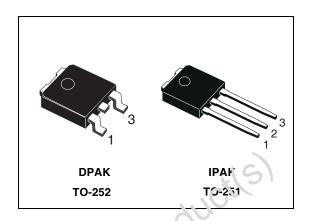
Description

The device is manufactured using high voltage Multi-Epitaxial Planar technology for high switching speeds and high voltage capability.

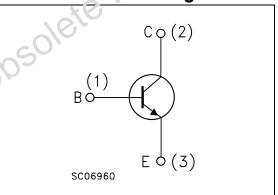
Thanks to an increased intermediate layer, it has an intrinsic ruggedness which enables the transistor to withstand an high collector current level during breakdown condition, without using the transil protection usually necessary in typical converters for lamp ballast.

Applications

■ Electronic ballast for fluorescent lighting



Internal schematic diagram



೧೯ರ್ಷ codes

Part number	Marking	Package	Packaging	
BULD1101ET4	BULD1101E	DPAK	Tape & reel	
BULD1101E-1	BULD1101E	IPAK	Tube	

May 2007 Rev 2 1/11

Electrical ratings BULD1101E

1 Electrical ratings

Table 1. Absolute maximum rating

Symbol	Parameter	Value	Unit
V _{CES}	Collector-emitter voltage (V _{BE} = 0)	1100	٧
V _{CEO}	Collector-emitter voltage (I _B = 0)	450	٧
V _{EBO}	Emitter-base voltage (I _C = 0)	12	٧
I _C	Collector current	3	Α
I _{CM}	Collector peak current (t _P < 5ms)	6	Α
I _B	Base current	1.5	Α
I _{BM}	Base peak current (t _P < 5ms)	3	Α
P _{tot}	Total dissipation at T _c = 25°C	35	W
T _{stg}	Storage temperature	-65 to 150	ů
TJ	Max. operating junction temperature	150	°C

Table 2. Thermal data

s	Symbol	Parameter	Value	Unit	
	R _{thj-case}	Thermal resistance junction-case max		3.57	°C/W
F	R _{thj-amb}	Thermal resistance junction-amb	max	100	°C/W
Opsolei	eP	roducile			

2 Electrical characteristics

 $(T_{case} = 25^{\circ}C \text{ unless otherwise specified})$

Table 3. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{CES}	Collector cut-off current (V _{BE} =0V)	V _{CE} =1100V			100	μА
V _{(BR)EBO}	Emitter-base breakdown voltage ($I_C = 0$)	I _E =1mA	12		24	V
V _{CEO(sus)} (1)	Collector-emitter sustaining voltage (I _B = 0)	I _C =100mA	450			٧
V _{CE(sat)} (1)	Collector-emitter saturation voltage	$\begin{split} &I_{C}\!=\!1A & I_{B}\!=\!0.2A \\ &I_{C}\!=\!1A & I_{B}\!=\!0.2A & T_{J}\!=\!125^{\circ}C \end{split}$		0.25 0.6	1 1.5	V V
V _{BE(sat)} (1)	Base-emitter saturation voltage	I _C =1A I _B =0.2A	00		1.5	V
		I _C =0.25A V _{CE} =5V	20	38	80	
h _{FE}	DC current gain	$I_{C} = 0.25A V_{CE} = 5V T_{J} = 125^{\circ}C$	23	44	85	
''''		$I_C = 2A$ $V_{CE} = 5V$	6	10	18	
		$I_C = 2A$ $V_{CE} = 5V$ $T_J = 125$ °C	4	7	16	
	Resistive load	V _{CC} =125V I _C =2.5A				
ts	Storage time	$I_{B1} = -I_{B2} = 0.5A$ $t_p = 300 \mu s$			2	μs
t _f	Fall time	V _{BE(off)} =-5V (see fig.10)		400	700	ns
E _{ar}	Repetitive avalanche energy	$\begin{array}{ll} L = 2mH & C = 1.8nF \\ I_{BR} \leq 2.5A & (see fig.11) \end{array}$	6			mJ

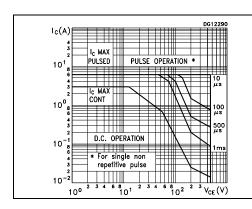
Note (1) Pulsed duration = 300μs, duty cycle ≤1.5%

Electrical characteristics BULD1101E

2.1 Typical characteristic

Figure 1. Safe operating area

Figure 2. Derating curve



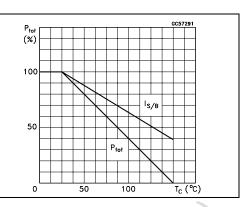
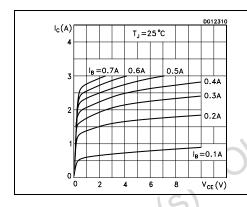


Figure 3. Output characteristics

Figure 4. Collector-emitter saturation voltage



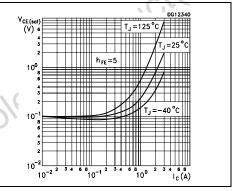
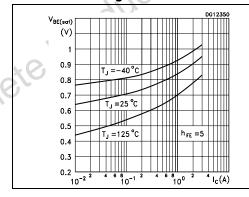


Figure 5. Base-emitter saturation voltage

Figure 6. DC current gain



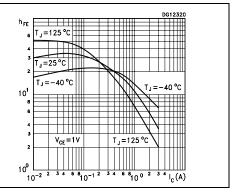
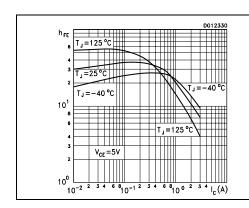


Figure 7. DC current gain

Figure 8. Resistive load switching times



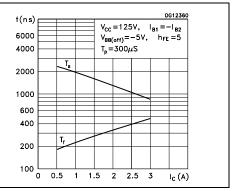
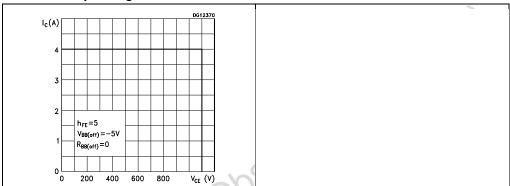


Figure 9. Reverse biased safe operating area

Obsolete Product(s)



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Electrical characteristics BULD1101E

2.2 Test circuit

Figure 10. Resistive load switching test circuit

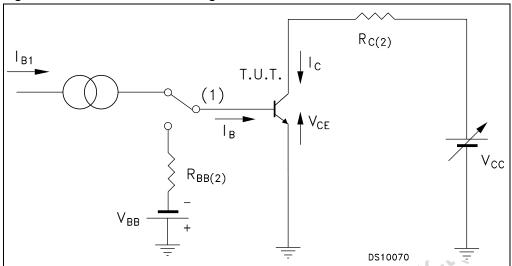
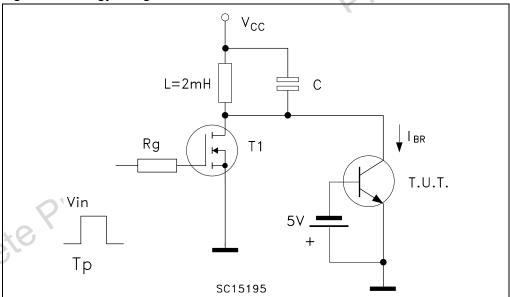


Figure 11. Energy rating test circuit



3 Package mechanical data

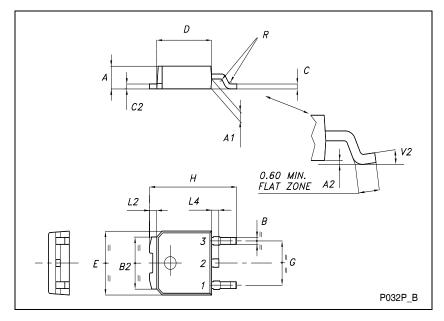
In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Obsolete Product(s). Obsolete Product(s)

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TO-252 (DPAK) MECHANICAL DATA

DIM.	mm			inch		
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
С	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
Е	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
Н	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°

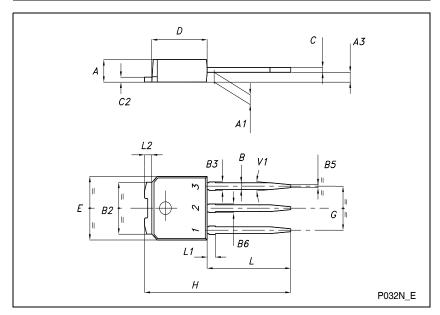




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TO-251 (IPAK) MECHANICAL DATA

DIM.	mm			inch		
DIW.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A3	0.70		1.30	0.028		0.051
В	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
В3			0.85			0.033
B5		0.30			0.012	
B6			0.95			0.037
С	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.237		0.244
Е	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
Н	15.90		16.30	0.626		0.642
L	9.00		9.40	0.354		0.370
L1	0.80		1.20	0.031		0.047
L2		0.80	1.00		0.031	0.039
V1		10°			10°	



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Obsolete

Revision history BULD1101E

4 Revision history

Table 4. Revision history

Date	Revision	Changes	
20-Apr-2003	1	Initial release.	
07-May-2007	2	The document has been reformatted.	



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